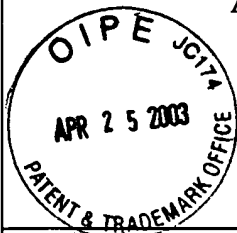


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	4,302,721	11/24/81	Urbanek et al.			05/15/79
	4,750,141	06/07/88	Judell et al.			11/26/85
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	6,360,133	03/19/02	Campbell et al.			06/17/99
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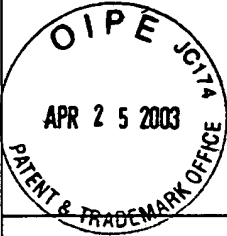
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SRB	6,479,902	11/12/02	Lopatin et al.			06/29/00
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SRB	2002/0185658	12/12/02	Inoue et al.			06/14/01
SRB	2002/0193902	12/19/02	Shanmugasundram et al.			06/18/02
SRB	2002/0197745	12/26/02	Shanmugasundram et al.			08/31/01
SRB	2002/0197934	12/26/02	Paik			11/30/01
SRB	2002/0199082	12/26/02	Shanmugasundram et al.			06/18/02
SRB	6,503,839	01/07/03	Gonzales et al.			07/03/01
SRB	2003/0020909	01/30/03	Adams et al.			04/09/01
SRB	2003/0020928	01/30/03	Ritzdorf et al.			07/09/01
SRB	6,517,413	02/11/03	Hu et al.			10/25/00

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						Yes	No
SRB	61-66104	04/04/86	Japan	/	/	X	
SRB	3-202710	09/04/91	Japan	/	/	X	
SRB	8-23166	01/23/96	Japan	/	/	X	
SRB	9-246547	09/19/97	Japan	/	/	X	
SRB	WO 98/05066	02/05/98	WIPO	/	/	X	
SRB	10-34522	02/10/98	Japan	/	/	X	
SRB	0 869 652	10/07/98	Europe	/	/	X	
SRB	WO 99/09371	02/25/99	WIPO	/	/	X	
SRB	0 910 123	04/21/99	Europe	/	/	X	
SRB	0 932 194	07/28/99	Europe	/	/	X	
SRB	WO 00/00874	01/06/00	WIPO	/	/	X	
SRB	2000-183001	06/30/00	Japan	/	/	X	

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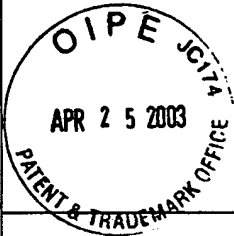
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						Yes	No
	1 071 128	01/24/01	Europe	RECEIVED APR 28 2003 Technology Center 2100		X	
	WO 01/18623	03/15/01	WIPO			X	
	WO 01/25865	04/12/01	WIPO			X	
	434103	05/16/01	Taiwan			X	
	436383	05/28/01	Taiwan			X	
	455938	09/21/01	Taiwan			X	
	455976	09/21/01	Taiwan			X	
	2001-284299	10/12/01	Japan			X	
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